

MT18FL

- MicroThin为附18 μ m载体铜箔的超薄铜箔。
MicroThin is ultra thin foil with 18 μ m carrier foil.
- 适用于线宽/线距(L/S) = 20/20或以下之应用。
Usable for fine pitch pattern L/S = 20/20 or less formation.
- 与MT18Ex相比较, 其更低的粗糙度更适用于极细线路之应用。
Lower profile compare with MT18Ex, more suitable for very fine pattern.

用途/Application

- IC封装基板
/Semiconductor Package

构成/Composition



生产地点/Production Site

- 日本 / Japan

代表性特性数据/Representative data

	μ m	Area weight (g/m ²)	Laminate side Rz(μ m)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)@FR-4
MT18FL	1.5	18	1.3	-	-	1.2
	2	21	1.3	-	-	1.2
	3	30	1.3	-	-	1.2

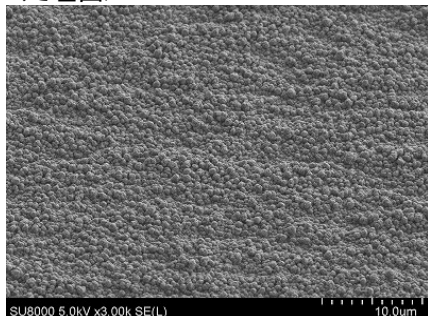
※上述表列为代表性数据非保证值

This is representative data, not guaranteed.

※Peel Strength为增镀到35 μ m厚度之后的测试值

Evaluated after plated up to 35 μ m.

处理面/Laminate side



阻剂面/ resist side

